



Material Content Data Sheet



Sales Product Name	TLE4997E2			Issued	20. July 2018			
MA#	MA001625628							
Package	PG-SSO-3-10			Weight*	143.11 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.537	3.17	3.17	31699	31699
leadframe	inorganic material	silicon	7440-21-3	0.020	0.01		138	
	non noble metal	titanium	7440-32-6	0.099	0.07		691	
	non noble metal	chromium	7440-47-3	0.297	0.21		2073	
wire	non noble metal	copper	7440-50-8	98.494	68.83	69.12	688223	691125
	noble metal	gold	7440-57-5	0.047	0.03	0.03	326	326
	encapsulation	organic material	carbon black	1333-86-4	0.350	0.24		2444
encapsulation	plastics	epoxy resin	-	4.420	3.09		30881	
	inorganic material	silicondioxide	60676-86-0	27.026	18.88	22.21	188842	222167
leadfinish	non noble metal	tin	7440-31-5	5.779	4.04	4.04	40384	40384
plating	noble metal	silver	7440-22-4	0.604	0.42	0.42	4217	4217
glue	plastics	epoxy resin	-	0.289	0.20		2016	
	noble metal	silver	7440-22-4	1.154	0.81	1.01	8066	10082
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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